ABSTRACT

A multi-layer circuit board is manufactured by laminating and bonding together a plurality of resin films, on each of which a circuit pattern is directly drawn by injecting ink. The ink includes metal particles, having a diameter in the order of nanometers, dispersed therein. At the same time when the laminated resin films are bonded together under pressure and heat, the metal particles in the ink are sintered, thereby forming a solid electrical circuit printed on the resin film. Since the circuit pattern is directly drawn on the resin film, the process of manufacturing the multi-layer circuit board is simplified.